



**Material Composition Declaration**  
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information
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**Supplier Information**


<b>Company name*</b> onsemi	Company unique ID	Unique ID Authority	<b>Response Date*</b> 2023-06-08
<b>Contact Name</b> Product-Env-Stewards	Title - Contact Product Enviro Compliance	<b>Phone - Contact*</b> NA	<b>Email - Contact*</b> Product-Env-Stewards@onsemi.com
<b>Authorized Representative*</b> Product-Env-Stewards	Title - Representative Product Enviro Compliance	<b>Phone - Representative*</b> NA	<b>Email - Representative*</b> Product-Env-Stewards@onsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
	R3910-CFAB-E1T	Preconfig DSP: Rhythm Tape & Reel 250/Reel	2023-06-08			60.897373	mg	Each

**Manufacturing Process Information**

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
SnAgCu	CU Alloy	3	260 C	30 seconds	3

Comments  
**ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)**  
**For more information regarding material composition please refer to page 3**

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.</p>			
<b>RoHS Declaration *</b>	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions		<b>Supplier Acceptance *</b> Accepted
<b>Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.</b>			
Exemption List Version	EL-2011/534/EU		
<b>Declaration Signature</b>			
<b>Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.</b>			
Supplier Digital Signature	Rastislav Drska		

**Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitor	0.9	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.147	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0058	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0232	mg
			Supplier	Misc.	Proprietary Data		0.049	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.294	mg
			B	Nickel (Ni)	7440-02-0		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		0.261	mg
Die	4.889605	mg	Supplier	Silicon (Si)	7440-21-3		4.8896	mg
Laminate Board	36.830296	mg		Defoamers	n/a		0.0006	mg
			Supplier	Phthalocyanine blue	N/A		0.0123	mg
			Supplier	Organic Filler	N/A		0.0123	mg
			Supplier	Acrylate resin	N/A		0.8572	mg
			Supplier	Dipropyleneglycolmonomethylether	34590-97-8		0.0019	mg
			Supplier	Cured Thermosetting Resin	Proprietary Data		5.6678	mg
			Supplier	Silica	Proprietary Data		0.0001	mg
			Supplier	Talc	14807-96-6		0.0612	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		0.0037	mg
			Supplier	Naphthalene	91-20-3		0.0003	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		5.6678	mg
			Supplier	Photoinitiator	Proprietary Data		0.0006	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0005	mg
			B	Nickel (Ni)	7440-02-0		0.0009	mg
			Supplier	Gold (Au)	7440-57-5		0.0004	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		0.0006	mg
			Supplier	Copper (Cu)	7440-50-8		23.8076	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.7347	mg
Mold Compound-Black	14.5	mg		Epoxy resin	proprietary data		1.16	mg
			Supplier	Phenol Resin	Proprietary Data		0.725	mg
			Supplier	Metal Hydroxide	Proprietary Data		0.145	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.625	mg
			Supplier	Carbon Black (C)	1333-86-4		0.145	mg

			Supplier	Fused Silica (SiO2)	60676-86-0		8.7	mg
Resistor	0.04067	mg	Supplier	C.I. Pigment Black	68186-91-4		0.0005	mg
			Supplier	Epoxy Resin	25068-38-6		0.0003	mg
			Supplier	Glass Frit	65997-18-4	7c	0	mg
			Supplier	Boron (B)	7440-42-8		0	mg
			Supplier	Silver (Ag)	7440-22-4		0.0014	mg
			Supplier	Tin (Sn)	7440-31-5		0.0027	mg
			B	Bismuth Trioxide (Bi2O3)	1304-76-3		0.0003	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0006	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0006	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0284	mg
			Supplier	Ruthenium Oxide (RuO2)	12036-10-1		0.0004	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0	mg
			B	Nickel (Ni)	7440-02-0		0.0052	mg
Solder Paste	3.089286	mg	Supplier	2-(2-Hexyloxyethoxy) ethanol	112-59-4		0.1236	mg
			Supplier	Denatured Acid Hydrogenation Rosin	Proprietary		0.1236	mg
			Supplier	Dimer Acid	Proprietary		0.0618	mg
			Supplier	Silver (Ag)	7440-22-4		0.0927	mg
			Supplier	Tin (Sn)	7440-31-5		2.6568	mg
			Supplier	Copper (Cu)	7440-50-8		0.0309	mg
Wire Bond - Au	0.647515	mg	Supplier	Gold (Au)	7440-57-5		0.6475	mg